

P-Channel 30-V (G-S) MOSFET

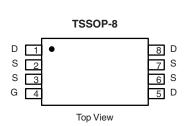
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
	0.010 at V _{GS} = - 4.5 V	- 9.0		
-30	0.012 at V _{GS} = - 2.5 V	- 7.8		
	0.016 at V _{GS} = - 1.8 V	- 6.0		

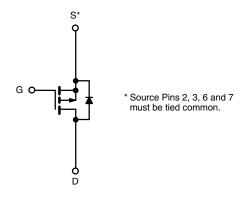
FEATURES

- Halogen-free
- Trench Power MOSFETs









P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unles		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	-30		V
Gate-Source Voltage		V _{GS}	± 12		
Operation of Decision (T. 150,00)	T _A = 25 °C	- I _D	- 9.0	-7.8	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		- 6.8	-5.8	
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	- 30		Α
Continuous Source Current (Diode Conduction) ^a		I _S	- 1.35	- 0.95	
Manipus Barra Discipation	T _A = 25 °C	P _D	1.5	1.05	W
Maximum Power Dissipation ^a	T _A = 70 °C		1.0	0.67	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian and Lunching to Aughington	t ≤ 10 s	R_{thJA}	65	83	
Maximum Junction-to-Ambient ^a	Steady State	¹¹thJA	100	120	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	43	52	

Notes: a. Surface Mounted on 1" x 1" FR4 board.

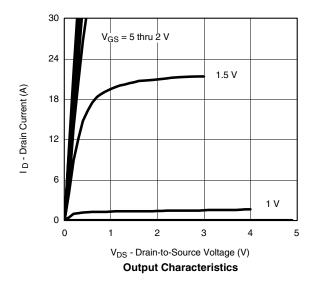


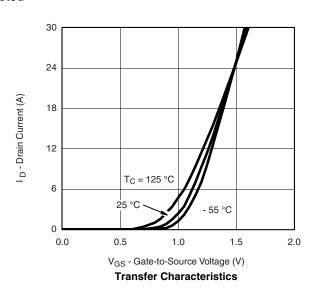
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Gate Threshold Voltage V _{GS(th)}		$V_{DS} = V_{GS}, I_D = -450 \mu A$ - 0.45		-	1.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V		- 1			
Zero Gate Voltage Drain Current		$V_{DS} = -30V, V_{GS} = 0 V, T_{J} = 70 ^{\circ}C$			- 25	μΑ	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 4.5 V	- 20			Α	
	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8.0 A		0.010			
Drain-Source On-State Resistance ^a		V _{GS} = - 2.5 V, I _D = - 7.0 A		0.012		Ω	
		V _{GS} = - 1.8 V, I _D = - 5.8 A		0.016			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 8.0 A		44		S	
Diode Forward Voltage ^a	V_{SD}	I _S = - 1.5 A, V _{GS} = 0 V		- 0.56	- 1.1	V	
Dynamic ^b				•			
Total Gate Charge	Qg			46	70	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -8.0 \text{ A}$		5			
Gate-Drain Charge	Q_{gd}			15.5		1	
Turn-On Delay Time	t _{d(on)}			45	70		
Rise Time	t _r	V _{DD} = - 10 V, <u>R</u> = 6 Ω		85	130		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω		220	400	ns	
Fall Time	t _f			155	235		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 1.5 A, di/dt = 100 A/μs		140	210		

- Notes: a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

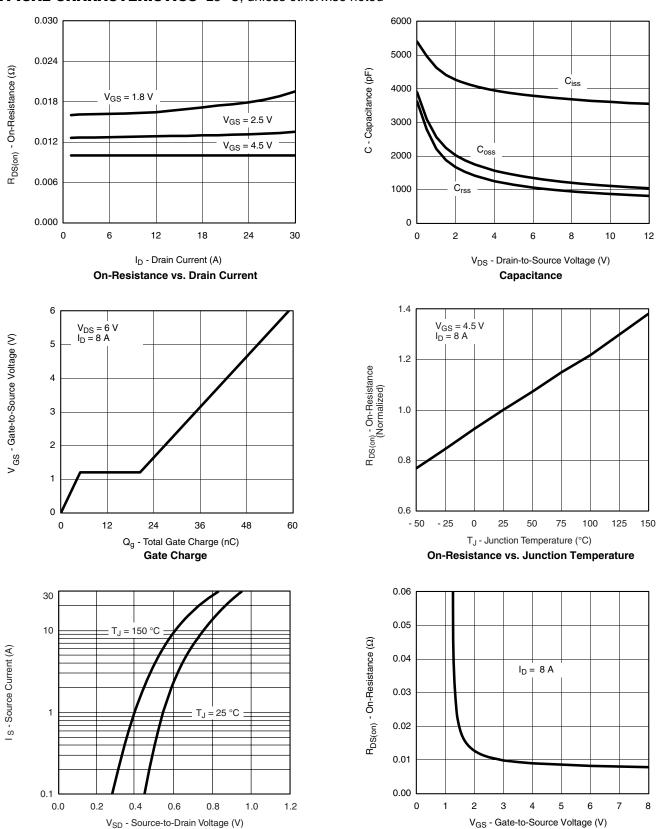
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







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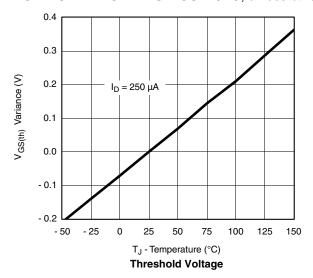
服务热线:400-655-8788

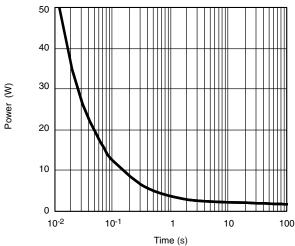
Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

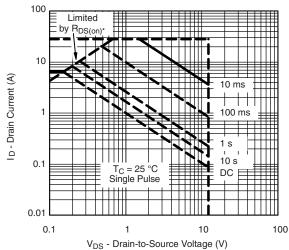


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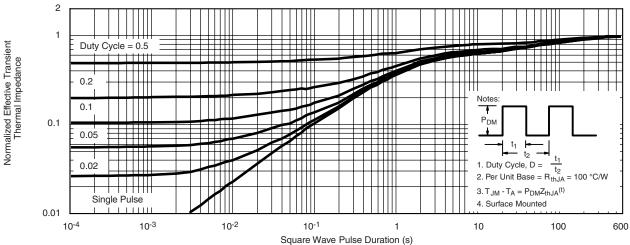


Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

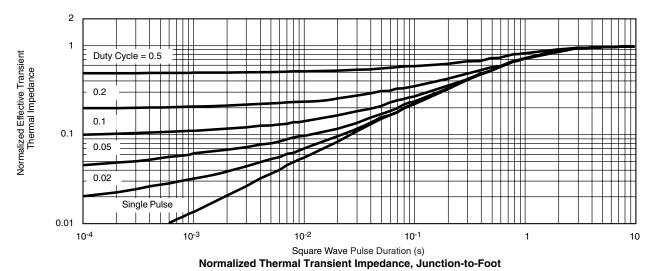
Safe Operating Area, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient



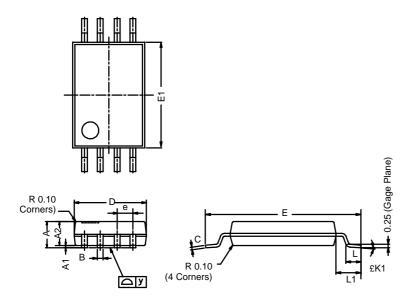
TYPICAL CHARACTERISTICS 25 $^{\circ}\text{C}$, unless otherwise noted





TSSOP: 8-LEAD

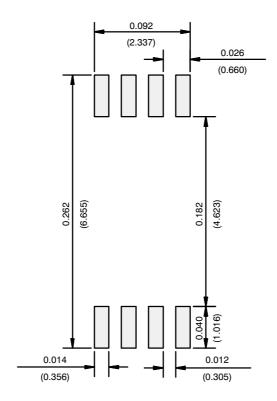
JEDEC Part Number: MO-153



	MILLIMETERS				
Dim	Min	Nom	Max		
Α	_	_	1.20		
A ₁	0.05	0.10	0.15		
A ₂	0.80	1.00	1.05		
В	0.19	0.28	0.30		
С	-	0.127	-		
D	2.90	3.00	3.10		
E	6.20	6.40	6.60		
E ₁	4.30	4.40	4.50		
е	-	0.65	-		
L	0.45	0.60	0.75		
L ₁	0.90	1.00	1.10		
Y	_	-	0.10		
£K1	0°	3°	6°		
ECN: S-03946—Rev. G, 09-Jul-01 DWG: 5844					



RECOMMENDED MINIMUM PADS FOR TSSOP-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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